Switch-mode Power Rectifier

DPAK Surface Mount Package

MURD330T4G, SURD8330T4G, SURD8330T4G-VF01

These state-of-the-art devices are designed for use in switching power supplies, inverters and as free wheeling diodes.

Features

- Low Forward Voltage Drop
- Low Leakage
- Ultra-Fast Recovery Time
- SURD8 Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Rated Reverse Voltage	V _R	300	V
Average Rectified Forward Current (T _C = 170°C)	IF	3.0	Α
Non-Repetitive Peak Surge Current	I _{FSM}	75	Α
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



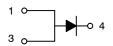
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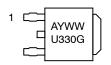
ULTRAFAST RECTIFIER 3 A, 300 V



CASE 369C



MARKING DIAGRAM



U330 = Specific Device Code = Assembly Location*

= Year ww = Work Week = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping [†]
MURD330T4G	DPAK (Pb-Free)	2,500/Tape & Reel
SURD8330T4G	DPAK (Pb-Free)	2,500/Tape & Reel
SURD8330T4G- VF01	DPAK (Pb-Free)	2,500/Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{*} The Assembly Location Code (A) is front side optional. In cases where the Assembly Location is stamped in the package bottom (molding ejecter pin), the front side assembly code may be blank.

MURD330T4G, SURD8330T4G, SURD8330T4G-VF01

THERMAL CHARACTERISTICS

Characteristics	Symbol	Value	Unit
Thermal Resistance – Junction-to-Case	$R_{ heta JC}$	2	°C/W
Thermal Resistance – Junction–to–Ambient (Note 1)	$R_{\theta JA}$	49	°C/W

^{1.} Rating applies when surface mounted on a 700 mm², 1 oz Cu heat spreader.

ELECTRICAL CHARACTERISTICS

Characteristics	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage Drop ($I_F = 3 \text{ A}, T_J = 25^{\circ}\text{C}$) ($I_F = 3 \text{ A}, T_J = 150^{\circ}\text{C}$)	V _F	1.15 0.92	V
Maximum Instantaneous Reverse Current $(T_J = 25^{\circ}C, 300 \text{ V})$ $(T_J = 150^{\circ}C, 300 \text{ V})$	I _R	5 500	μΑ
Maximum Reverse Recovery Time (I _F = 1 A, di/dt = 50 A/ μ s, V _R = 30 V, T _J = 25°C)	t _{rr}	50	ns
ESD Ratings: Machine Model = C Human Body Model = 3B		> 400 > 8000	V
Typical Peak Reverse Recovery Current ($I_F = 1.0 \text{ A}, \text{ di/dt} = 50 \text{ A/}\mu\text{s}$)	I _{RM}	1.5	А

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS

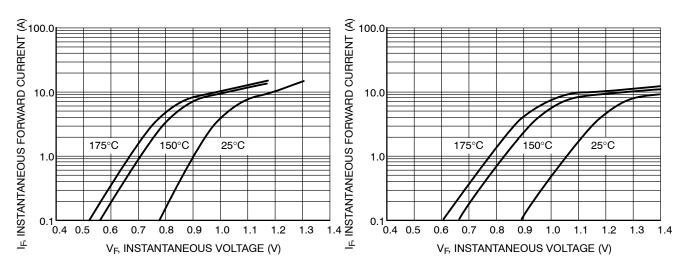


Figure 1. Typical Forward Voltage

Figure 2. Maximum Forward Voltage

MURD330T4G, SURD8330T4G, SURD8330T4G-VF01

TYPICAL CHARACTERISTICS

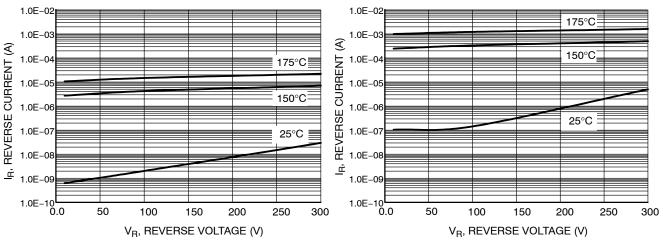


Figure 3. Typical Reverse Voltage

Figure 4. Maximum Reverse Voltage

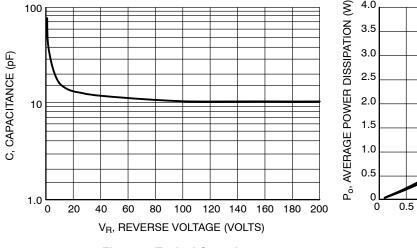


Figure 5. Typical Capacitance

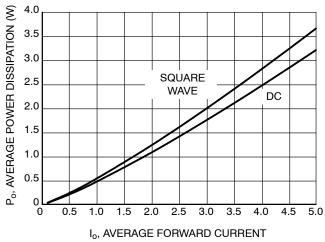


Figure 6. Power Dissipation

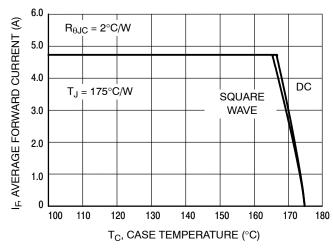


Figure 7. Current Derating, Case

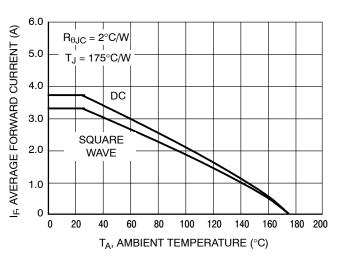
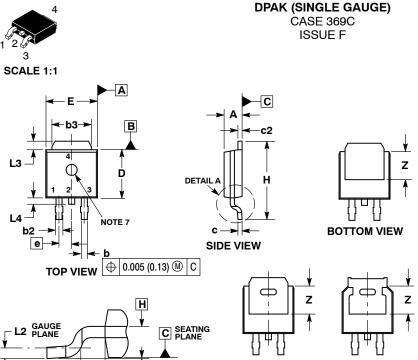
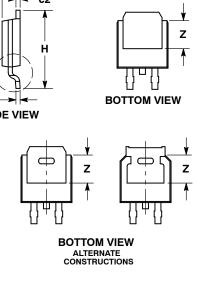


Figure 8. Current Derating, Ambient







STYLE 5:

STYLE 4:

SITLE I.	STILE 2.	311	LE 3.	31	TLE 4.	STILE 5.
PIN 1. BASE	PIN 1. GA	ΓE PII	N 1. ANODE	F	PIN 1. CATHODE	PIN 1. GATE
COLLE	CTOR 2. DR	AIN	CATHOI	DE	ANODE	2. ANODE
EMITTE	R 3. SO	URCE	ANODE		GATE	CATHODE
COLLE	CTOR 4. DR	AIN	4. CATHO	DE	ANODE	4. ANODE
STYLE 6:	STYLE 7:	STYLE 8:		STYLE 9:		STYLE 10:
PIN 1. MT1	PIN 1. GATE	PIN 1. N/		PIN 1. A		PIN 1. CATHODE
2. MT2	COLLECTOR	2. CA	ATHODE	2. C	ATHODE	2. ANODE
GATE	EMITTER	3. AN	NODE	3. R	ESISTOR ADJUST	CATHODE
4. MT2	COLLECTOR	R 4. CA	ATHODE	4. C	ATHODE	4. ANODE

STYLE 3:

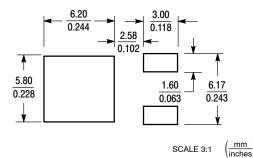
SOLDERING FOOTPRINT*

Α1

STYLE 2:

DETAIL A ROTATED 90° CW

STYLE 1:



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DATE 21 JUL 2015

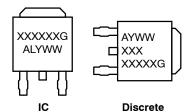
NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN DI-
- MENSIONS b3, L3 and Z.
 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.006 INCHES PER SIDE.
 5. DIMENSIONS D AND E ARE DETERMINED AT THE
- OUTERMOST EXTREMES OF THE PLASTIC BODY.

 6. DATUMS A AND B ARE DETERMINED AT DATUM
- 7. OPTIONAL MOLD FEATURE.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.086	0.094	2.18	2.38
A1	0.000	0.005	0.00	0.13
b	0.025	0.035	0.63	0.89
b2	0.028	0.045	0.72	1.14
b3	0.180	0.215	4.57	5.46
С	0.018	0.024	0.46	0.61
c2	0.018	0.024	0.46	0.61
D	0.235	0.245	5.97	6.22
E	0.250	0.265	6.35	6.73
е	0.090	BSC	2.29 BSC	
Н	0.370	0.410	9.40	10.41
L	0.055	0.070	1.40	1.78
L1	0.114 REF		2.90 REF	
L2	0.020 BSC		0.51	BSC
L3	0.035	0.050	0.89	1.27
L4		0.040		1.01
Z	0.155		3.93	

GENERIC MARKING DIAGRAM*



XXXXXX = Device Code = Assembly Location Α L = Wafer Lot Υ = Year

WW = Work Week = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	DPAK (SINGLE GAUGE)		PAGE 1 OF 1

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